

DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

TIN-CONTAINING PLATING BATH

the specification of which is attached hereto unless the following is checked

☒ was filed on January 22, 2004 as United States Application Number or PCT International

Application Number PCT/JP2004/000524 and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) – (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application for which priority is claimed.

(List prior foreign applications. See note A)

2003-15562
(Number)

Japan
(Country)

24/01/2003
(Day/Month/Year Filed)

☒ Yes ☐ No

2003-432338
(Number)

Japan
(Country)

26/12/2003
(Day/Month/Year Filed)

☒ Yes ☐ No

(Number)

(Country)

(Day/Month/Year Filed)

☐ Yes ☐ No

(Number)

(Country)

(Day/Month/Year Filed)

☐ Yes ☐ No

(See note B)

☐ See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(List prior U.S. Applications)

Status

(Application Serial No.)

(Filing Date)

☐ Patented ☐ Pending ☐ Abandoned

(Application Serial No.)

(Filing Date)

☐ Patented ☐ Pending ☐ Abandoned

(Application Serial No.)

(Filing Date)

☐ Patented ☐ Pending ☐ Abandoned

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

23850

PATENT TRADEMARK OFFICE

Please direct all communications to the following address:

23850

PATENT TRADEMARK OFFICE

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, ' 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See note C)

Full name of sole or first inventor (given name, family name)	MASUDA Akihiro
Inventor's signature	<u>Akihiro Masuda</u> Date June 24, 2005
Residence	Sanda-shi, Hyogo 6691339, Japan Citizenship Japan
Post Office Address	c/o Sanda Plant of MITSUBISHI MATERIALS CORPORATION, 12-6, Technopark, Sanda-shi, Hyogo 6691339, Japan

Full name of second inventor (given name, family name)	KOHINATA Masayoshi
Inventor's signature	<u>Masayoshi Kohinata</u> Date June 24, 2005
Residence	Sanda-shi, Hyogo 6691339, Japan Citizenship Japan
Post Office Address	c/o Sanda Plant of MITSUBISHI MATERIALS CORPORATION, 12-6, Technopark, Sanda-shi, Hyogo 6691339, Japan

Full name of third inventor (given name, family name)	OBATA Keigo
Inventor's signature	<u>Keigo Obata</u> Date June 24, 2005
Residence	Akashi-shi, Hyogo 6740093, Japan Citizenship Japan
Post Office Address	c/o DAIWA FINE CHEMICALS CO., LTD., 21-8, Minami-futami, Futami-cho, Akashi-shi, Hyogo 6740093, Japan

Full name of fourth inventor (given name, family name)	YOSHIMOTO Masakazu
Inventor's signature	<u>Masakazu Yoshimoto</u> Date June 24, 2005
Residence	Akashi-shi, Hyogo 6740093, Japan Citizenship Japan
Post Office Address	c/o DAIWA FINE CHEMICALS CO., LTD., 21-8, Minami-futami, Futami-cho, Akashi-shi, Hyogo 6740093, Japan

Full name of fifth inventor (given name, family name)	TSUJI Kiyotaka
Inventor's signature	<u>Kiyotaka Tsuji</u> Date June 24, 2005
Residence	Kobe-shi, Hyogo 6520806, Japan Citizenship Japan
Post Office Address	c/o ISHIHARA CHEMICAL CO., LTD., 5-26, Nishi-yanagiwara-cho, Hyogo-ku, Kobe-shi, Hyogo 6520806, Japan

Full name of sixth inventor (given name, family name)

UCHIDA Ei

Inventor's signature

Ei Uchida

Date

June 24, 2005

Residence

Kobe-shi, Hyogo 6520806, Japan

Citizenship

Japan

Post Office Address

c/o ISHIHARA CHEMICAL CO., LTD., 5-26, Nishi-yanagiwara-cho,
Hyogo-ku, Kobe-shi, Hyogo 6520806, Japan

Full name of seventh inventor (given name, family name)

ORI Keiji

Inventor's signature

Keiji Ori

Date

June 24, 2005

Residence

Kobe-shi, Hyogo 6520806, Japan

Citizenship

Japan

Post Office Address

c/o ISHIHARA CHEMICAL CO., LTD., 5-26, Nishi-yanagiwara-cho,
Hyogo-ku, Kobe-shi, Hyogo 6520806, Japan

Full name of eighth inventor (given name, family name)

EIKAWA Masahiro

Inventor's signature

Masahiro, Eikawa

Date

June 24, 2005

Residence

Kobe-shi, Hyogo 6520806, Japan

Citizenship

Japan

Post Office Address

c/o ISHIHARA CHEMICAL CO., LTD., 5-26, Nishi-yanagiwara-cho,
Hyogo-ku, Kobe-shi, Hyogo 6520806, Japan